



MICROCHIP

QUALIFICATION REPORT SUMMARY

PCN #: MFOL-01YGFE706

Date:

January 23, 2026

Qualification of QMI2569 as a new die attach material for selected AT28C010, AT28C010E, AT28C256, AT28C256E, AT28C256F, AT28HC256, AT28HC256E and AT28HC256F device families available in 28L and 32L CERDIP (.600 In) and 32L CLCC (11.4x14x2.54mm) packages.



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CCB No: 8057

PACKAGE QUALIFICATION REPORT

Group D, Subgroup 3

Test Number (Reference)	Test Condition	SS/Acc.	Result
Electrical Test	As specified in the applicable Device specification	SS = 15 Acc = 0	Passed
Thermal Shock TM1011, cond. B 3G-OP-1805	Liquid to liquid thermal shock (-55 (+0/-10) to (125(+10/-0) C Perform 15 cycles		Passed
Temp Cycle TM1010, cond. C 3G-OP-1807	Air to air temp cycle (-65(+0/-10) to (150(+15/-0) C Perform 100 cycles		Passed
Moisture Resistance TM1004 3G-QA-1813	Temp: 25/65/-10 C Humidity: 90-100 %RH Perform 10 cycles		Passed
Visual Inspections	Visual Inspection Marking @ 3X Case, Leads, Seal @ 10 20X	SS = 15 Acc = 0	Passed
Electrical Test Endpoints	As specified in the applicable Device specification		Passed
Physical Dimension			Passed

PACKAGE QUALIFICATION REPORT

GROUP D, Subgroup 2 and 8

Test Number (Reference)	Test Condition	SS/Acc.	Result
<u>Subgroup 2</u> a) Lead Integrity TM2004, cond. B2 3H-QA-1803	Minimum samples size = 3 unit (For leadless chip package use condition D, SS=15 pad, Acc=0)	SS = 15 (Pads) Acc = 0	Passed
Visual	Examination 10 to 20X Breakage, Lossening		Passed
<u>Subgroup 8</u> Lid Torque TM2024 3H-QA-0602	Glass Frit Sealed unit only	SS = 5 (unit) Acc = 0	Passed